



MicroThin™

Introduction

MicroThin™ is a very low profile 3µm or 5µm copper foil with an 18µm or 35µm copper peelable carrier for high-density circuit applications. The releasing layer can be peeled-off after lamination and recycled.

Benefits

- Enables very fine circuit pattern production
- Easy to release carrier after high temperature lamination
- Even thickness of the thin foil
- Adequate peel strength

Product	Copper Thickness	Copper Foil	Carrier Thickness
MicroThin™	5 microns 3 microns	VLP	18 microns 35 microns

Properties	Unit	12µm *	18µm *	35µm *
Peel Strength B at room Temp	lbs/in	10	10	10
S4 (260°C x 20 sec)	lbs/in	7.5	10.5	15

* 3µm MicroThin™ foil after plating up to 12µm, 18µm, 35µm

The information contained in this specification is not intended to and does not create any warranties, express or implied, including any warranty of merchantability or fitness for a particular purpose. The actual performance of Mitsui materials will vary according to the customer's application.

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